In the Claims

Please cancel claims 1-18.

Please amend claims 19-25 as follows:

19.   (Amended once) A method of assembling a multi-chip device comprising [the acts of]:

fabricating an interposer having a first surface and a second surface;

populating the second surface with a plurality of conductive pads;

coupling a solder ball to each of <u>selected ones of the plurality of</u> [predefined] conductive pads; and

coupling at least one [of] semiconductor [dice] <u>die</u> and [a plurality of] <u>at least one</u> passive device[s] to the first surface, <u>wherein the at least one passive device is selected from a group comprising resistors, capacitors, and inductors.</u>

20.   (Amended once) The method of claim 19 further comprising [the act of] coupling the interposer to a substrate.

21.   (Amended once) The method of claim 19 wherein [the] fabricating [act] comprises fabricating the interposer <u>with</u> [out of an] organic material.

22.   (Amended once) The method of claim 19 wherein [the second] coupling at least one semiconductor die [act] comprises a C4 process.

23.   (Amended once) The method of claim 20 [19] further comprising [the act of] testing the semiconductor dice coupled to the interposer prior to [the] coupling the interposer to the substrate[act].

24.   (Amended once) The method of claim 19 further comprising [the act of] coupling a single chip carrier to the substrate.

25.   (Amended once) The method of claim 19 wherein [the second] coupling at least one semiconductor die [act] comprises coupling memory chips to the interposer.

Please add new claim 26 as follows:

26.   The method of claim 19, further comprising:

creating a plurality of contacts on the first surface; and

electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.

REMARKS

Claims 19-26 are pending. Independent claim 19 is a method claim for assembling the device recited in claim 1 of the parent application, which has previously